

Advanced Packaging Update: Market and Technology Trends

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The Advanced Packaging Update for September 2014 contains an analysis of the packages found in wearable electronics and some of the reliability issues that this segment faces. Product features, selling prices, and unit volumes for selected wearable products are provided. Recent developments in battery technology are described. A special section of the report covers OSAT assembly factory locations and the major packages at each site. A discussion of economic trends and the impact on the electronics industry is included.

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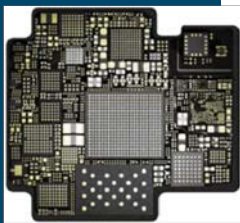
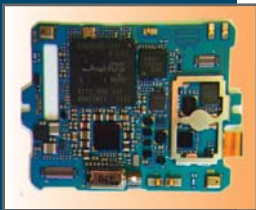
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4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759
Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com